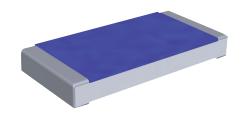
High Temperature Thick Film Chip Resistors



HTC Series

Features

- Operation to 200°C
- Excellent high temperature stability
- Improved working voltage ratings
- Pb-free wrap-around terminations
- Standard chip sizes available from 1206 to 2512





All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

Electrical Data

Characteristic	1206	2010	2512	
Resistance Range	1 Ω to 10M Ω ; ±1%, ±5% 10 Ω to 1M Ω ; ±0.5%, ±5%, ±1%			
150°C Power Rating	200mW	500mW	750mW	
Max Voltage Rating	200V	400V	500V	
Absolute TCR	± 100ppm/°C			
Operating Temperature	-55°C to +200°C			
Pad/Trace Area¹	80mm²	200mm²	300mm²	
Termination	Wrap-around Pb-free with leach resistant Ni barrier			

Note¹: Recommended minimum pad and adjacent trace area for each termination for rated power on FR4 PCB.

Environmental Data

Test	Method	Specification	
rest	wethod	Maximum ²	Typical
Load Life	MIL-STD-202 Method 108 (Rated Power for 1000hrs @ 150°C)	1.00%	0.25%
High Temperature Exposure	1000 hours @ 200°C	1.00%	0.20%
Short Time Overload	MIL-PRF-55342H (6.25X rated power for 5secs)	1.00%	0.10%
Moisture Resistance	MIL-STD-202 Method 106G	1.00%	0.25%
Thermal Shock	MIL-STD-202 Method 107G Condition B	0.25%	0.05%
Resistance to Soldering Heat	MIL-STD-202 Method 210F	0.25%	0.05%
Solderability	MIL-STD-202 Method 208 (245°C, 5 seconds)	>95% Coverage	

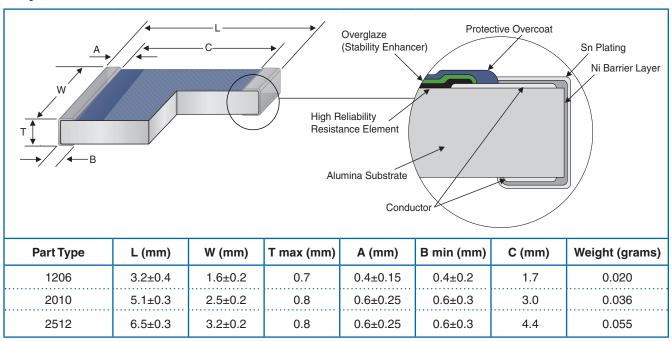
Note²: 0.01Ω added for all resistance values $<10\Omega$.

High Temperature Thick Film Chip Resistors





Physical Data



Construction:

Thick film resistor material, overglaze and organic protection are screen printed on a 96% alumina substrate. Wrap-around terminations have an electroplated Ni barrier and pure Sn matte finish, ensuring excellent `leach´ resistance properties and solderability.

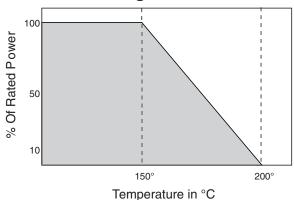
Marking:

Components are not marked. Reels are marked with type, value, tolerance, date code and quantity.

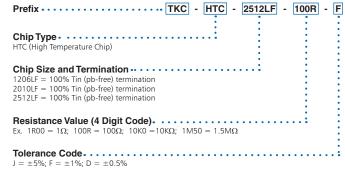
Solvent resistance

The body protection is resistant to all normal industrial cleaning solvents suitable for printed circuits.

Power Derating Data



Ordering Data



For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.